

Description

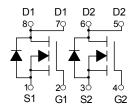
The SI9945BDY-T1 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

D1_{D1_{D2}D2}S1_{G1}S2_{G2}

SOP-8 (SO-8)

General Features

 $V_{DS} = 60V I_D = 6.5 A$ $R_{DS(ON)} < 36m\Omega @ V_{GS} = 10 V$ $R_{DS(ON)} < 48m\Omega @ V_{GS} = 4.5V$



Application

Battery protection

Load switch

Uninterruptible power supply

Dual N-Channel MOSFET

Package Marking and Ordering Information

Product ID	Pack	Marking	Qty(PCS)
SI9945BDY-T1	SOP-8(SO-8)	4828 XXX YYYY	3000

Absolute Maximum Ratings@T;=25°C(unless otherwise specified)

Symbol	Parameter	Rating	Units
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-Source Voltage	<u>+</u> 20	V
I _D @T _A =25°C	Drain Current, V _{GS} @ 4.5V ³	6.5	Α
I _D @T _A =70°C	Drain Current, V _{GS} @ 4.5V ³	5	Α
Ірм	Pulsed Drain Current ¹	30	Α
P _D @T _A =25°C	Total Power Dissipation	2.1	W
Тѕтс	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	°C
Rthj-a	Maximum Thermal Resistance, Junction- ambient ³	60	°C/W



Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics					•	
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	60		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =60V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V _{GS} =±20V,V _{DS} =0V	-	-	±100	nA
On Characteristics (Note 3)					•	
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250µA	1.0	1.4	2.0	V
Danier Courses On Otata Basistana	R _{DS(ON)}	V _{GS} =10V, I _D =6A	V _{GS} =10V, I _D =6A		36	mΩ
Drain-Source On-State Resistance		V _{GS} =4.5V, I _D =4A		34	48	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =6A		20	-	S
Dynamic Characteristics (Note4)	1		•			
Input Capacitance	C _{lss}	V 05VV 0V		1920		PF
Output Capacitance	Coss	V_{DS} =25V, V_{GS} =0V, F=1.0MHz		155		PF
Reverse Transfer Capacitance	C _{rss}	F=1.UMH2		116		PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	8	-	nS
Turn-on Rise Time	t _r	V_{DS} =30V, R_L =4.7 Ω	-	5	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{GEN} =3 Ω	-	29	-	nS
Turn-Off Fall Time	t _f		-	6	-	nS
Total Gate Charge	Qg	V -20VI -CA	-	50	-	nC
Gate-Source Charge	Q_{gs}	V_{DS} =30V, I_{D} =6A, V_{GS} =10V	-	8	-	nC
Gate-Drain Charge	Q_{gd}	V _{GS} -10V	-	16	-	nC
Drain-Source Diode Characteristic	cs					
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =6A	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	7	Α
Reverse Recovery Time	t _{rr}	TJ = 25°C, I _F =7A	-	35	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)} -$		43	-	nC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

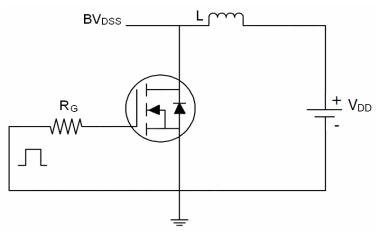
Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- **2.** Surface Mounted on FR4 Board, $t \le 10$ sec.
- **3.** Pulse Test: Pulse Width ≤ 300μ s, Duty Cycle ≤ 2%.
- 4. Guaranteed by design, not subject to production

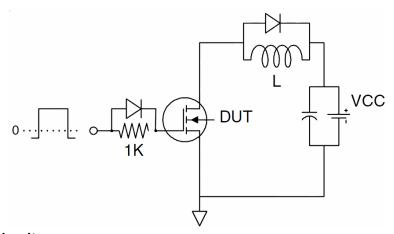


Test Circuit

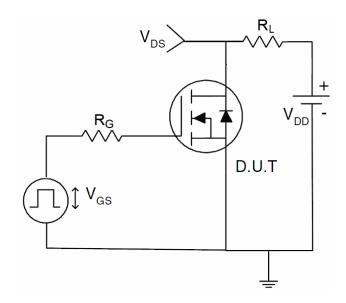
1) E_{AS} test Circuits



2) Gate charge test Circuit

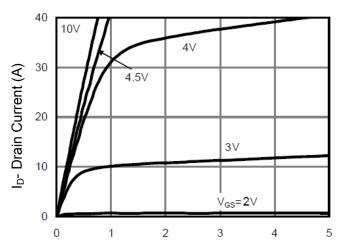


3) Switch Time Test Circuit





Typical Electrical and Thermal Characteristics (Curves)



Vds Drain-Source Voltage (V)



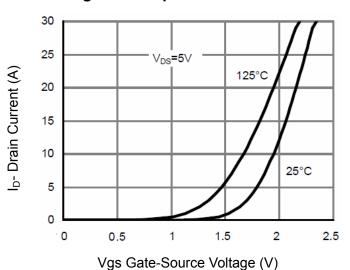


Figure 2 Transfer Characteristics

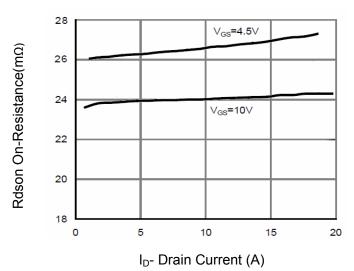


Figure 3 Rdson- Drain Current

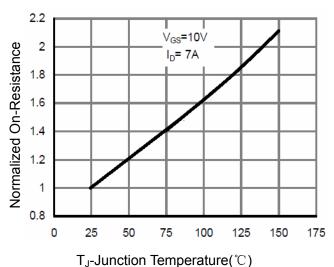


Figure 4 Rdson-JunctionTemperature

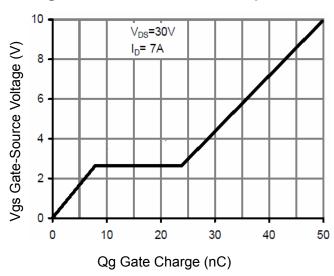


Figure 5 Gate Charge

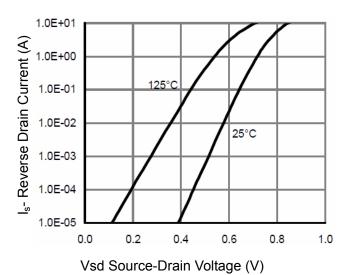


Figure 6 Source- Drain Diode Forward



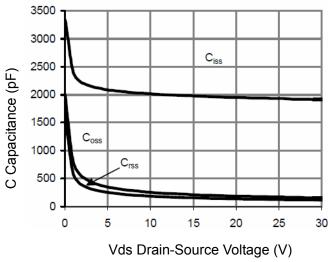


Figure 7 Capacitance vs Vds

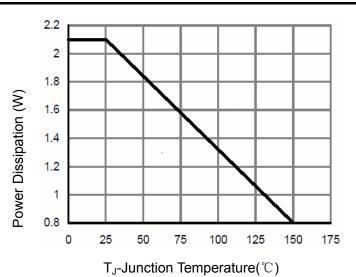


Figure 9 Power De-rating

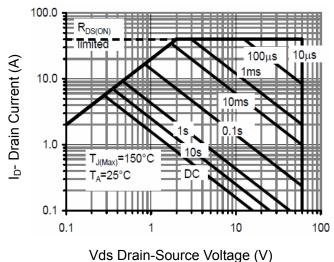


Figure 8 Safe Operation Area

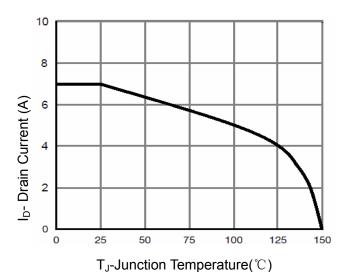


Figure 10 Current De-rating

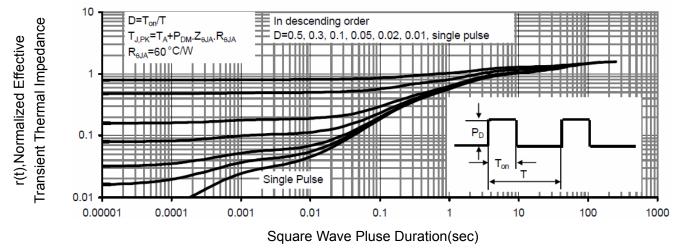
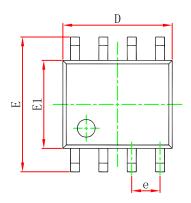
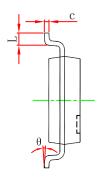


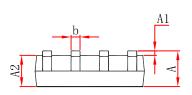
Figure 11 Normalized Maximum Transient Thermal Impedance



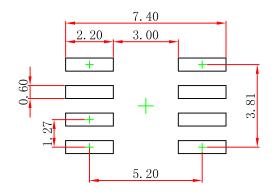
SOP-8(SO-8) Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
A	1.350	1.750	0.053	0.069	
A1	0.100	0. 250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0. 020	
c	0.170	0. 250	0.007	0.010	
D	4.800	5.000	0. 189	0. 197	
e	1. 270 ((BSC)	0.050 (BSC)		
E	5.800	6. 200	0. 228	0. 244	
E1	3.800	4.000	0. 150	0. 157	
L	0.400	1. 270	0.016	0.050	
θ	0°	8°	0°	8°	



- Note: 1.Controlling dimension:in millimeters.
- 2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.

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